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# Si827x Data Sheet

## 4 Amp ISOdriver with High Transient (dV/dt) Immunity

The Si827x isolators are ideal for driving power switches used in a wide variety of power supply, inverter, and motor control applications. The Si827x isolated gate drivers utilize Silicon Laboratories' proprietary silicon isolation technology, supporting up to 2.5 kVRMS withstand voltage per UL1577 and VDE0884. This technology enables industry leading common-mode transient immunity (CMTI), tight timing specifications, reduced variation with temperature and age, better part-to-part matching, and extremely high reliability. It also offers unique features such as separate pull-up/down outputs, driver shut-down on UVLO fault, and precise dead time programmability. The Si827x series offers longer service life and dramatically higher reliability compared to opto-coupled gate drivers.

The Si827x drivers utilize Silicon Labs' proprietary silicon isolation technology, which provides up to 2.5 kVRMS withstand voltage per UL1577 and fast 60 ns propagation times. Driver outputs can be grounded to the same or separate grounds or connected to a positive or negative voltage. The TTL level compatible inputs with >400 mV hysteresis are available in individual control input (Si8271/2/3/5) or PWM input (Si8274) configurations. High integration, low propagation delay, small installed size, flexibility, and cost-effectiveness make the Si827x family ideal for a wide range of isolated MOSFET/IGBT and SiC or GaN FET gate drive applications.

Automotive Grade is available for certain part numbers. These products are built using automotive-specific flows at all steps in the manufacturing process to ensure the robustness and low defectivity required for automotive applications.

### Industrial Applications

- Switch-mode Power Supplies
- Solar Power Inverters
- Motor control and drives
- Uninterruptible Power Supplies
- High-Power Class D Amplifiers

### Safety Regulatory Approvals

- UL 1577 recognized
  - Up to 2500 Vrms for 1 minute
- CSA component notice 5A approval
  - IEC 60950-1 (reinforced insulation)
- VDE certification conformity
  - VDE 0884 Part 10
- CQC certification approval
  - GB4943.1

### Automotive Applications

- On-board chargers
- Battery management systems
- Charging stations
- Traction inverters
- Hybrid Electric Vehicles
- Battery Electric Vehicles

### KEY FEATURES

- Single, dual, or high-side/low-side drivers
- Single PWM or dual digital inputs
- High dV/dt immunity:
  - 200 kV/μs CMTI
  - 400 kV/μs Latch-up
- Separate pull-up/down outputs for slew rate control
- Wide supply range:
  - Input supply: 2.5–5.5 V
  - Driver supply: 4.2–30 V
- Very low jitter of 200 ps p-p
- 60 ns propagation delay (max)
- Dedicated enable pin
- Silicon Labs' high performance isolation technology:
  - Industry leading noise immunity
  - High speed, low latency and skew
  - Best reliability available
- Compact packages:
  - 8-pin SOIC
  - 16-pin SOIC
  - QFN-14 (pin to pin compatible with LGA-14 packages)
- Wide temperature range:
  - –40 to 125 °C
- AEC-Q100 Qualified
- Automotive-grade OPNs available
  - AIAG compliant PPAP documentation support
  - IMDS and CAMDS listing support

## 1. Ordering Guide

Table 1.1. Si827x Ordering Guide

Ordering Part Number	Inputs	Driver Configuration	Output UVLO	Integrated Deglitcher	Dead Time Adjustable Range	Low Jitter	Package	Isolation Rating
<b>Products Available Now</b>								
Si8271AB-IS	VI	Single	5	N	N/A	Y	SOIC-8 NB	2.5 kVrms
Si8271BB-IS	VI	Single	8	N	N/A	Y	SOIC-8 NB	2.5 kVrms
Si8271DB-IS	VI	Single	12	N	N/A	Y	SOIC-8 NB	2.5 kVrms
Si8271GB-IS	VI	Single	3	N	N/A	Y	SOIC-8 NB	2.5 kVrms
Si8273AB-IS1	VIA/VIB	HS/LS	5	N	N/A	Y	SOIC-16 NB	2.5 kVrms
Si8273ABD-IS1	VIA/VIB	HS/LS	5	Y	N/A	N	SOIC-16 NB	2.5 kVrms
Si8273AB-IM1	VIA/VIB	HS/LS	5	N	N/A	Y	QFN-14	2.5 kVrms
Si8273ABD-IM1	VIA/VIB	HS/LS	5	Y	N/A	N	QFN-14	2.5 kVrms
Si8273DB-IS1	VIA/VIB	HS/LS	12	N	N/A	Y	SOIC-16 NB	2.5 kVrms
Si8273DBD-IS1	VIA/VIB	HS/LS	12	Y	N/A	N	SOIC-16 NB	2.5 kVrms
Si8273GB-IS1	VIA/VIB	HS/LS	3	N	N/A	Y	SOIC-16 NB	2.5 kVrms
Si8273GBD-IS1	VIA/VIB	HS/LS	3	Y	N/A	N	SOIC-16 NB	2.5 kVrms
Si8273BB-IS1	VIA/VIB	HS/LS	8	N	N/A	Y	SOIC-16 NB	2.5 kVrms
Si8273BBD-IS1	VIA/VIB	HS/LS	8	Y	N/A	N	SOIC-16 NB	2.5 kVrms
Si8274AB1-IS1	PWM	HS/LS	5	N	10-200	Y	SOIC-16 NB	2.5 kVrms
Si8274AB4D-IS1	PWM	HS/LS	5	Y	20-700	N	SOIC-16 NB	2.5 kVrms
Si8274AB1-IM1	PWM	HS/LS	5	N	10-200	Y	QFN-14	2.5 kVrms
Si8274AB4D-IM1	PWM	HS/LS	5	Y	20-700	N	QFN-14	2.5 kVrms
Si8274BB1-IS1	PWM	HS/LS	8	N	10-200	Y	SOIC-16 NB	2.5 kVrms
Si8274DB1-IS1	PWM	HS/LS	12	N	10-200	Y	SOIC-16 NB	2.5 kVrms
Si8274GB1-IS1	PWM	HS/LS	3	N	10-200	Y	SOIC-16 NB	2.5 kVrms
Si8274GB4D-IS1	PWM	HS/LS	3	Y	20-700	N	SOIC-16 NB	2.5 kVrms
Si8274GB1-IM1	PWM	HS/LS	3	N	10-200	Y	QFN-14	2.5 kVrms
Si8274GB4D-IM1	PWM	HS/LS	3	Y	20-700	N	QFN-14	2.5 kVrms
Si8275GB-IS1	VIA/VIB	Dual	3	N	N/A	Y	SOIC-16 NB	2.5 kVrms
Si8275GBD-IS1	VIA/VIB	Dual	3	Y	N/A	N	SOIC-16 NB	2.5 kVrms
Si8275AB-IM1	VIA/VIB	Dual	5	N	N/A	Y	QFN-14	2.5 kVrms
Si8275ABD-IM1	VIA/VIB	Dual	5	Y	N/A	N	QFN-14	2.5 kVrms
<b>Contact Silicon Labs Sales for These Options</b>								
Si8271ABD-IS	VI	Single	5	Y	N/A	N	SOIC-8 NB	2.5 kVrms
Si8271BBD-IS	VI	Single	8	Y	N/A	N	SOIC-8 NB	2.5 kVrms

Ordering Part Number	Inputs	Driver Configuration	Output UVLO	Integrated Deglitcher	Dead Time Adjustable Range	Low Jitter	Package	Isolation Rating
Si8271DBD-IS	VI	Single	12	Y	N/A	N	SOIC-8 NB	2.5 kVrms
Si8271GBD-IS	VI	Single	3	Y	N/A	N	SOIC-8 NB	2.5 kVrms
Si8273BB-IS1	VIA/VIB	HS/LS	8	N	N/A	Y	SOIC-16 NB	2.5 kVrms
Si8273BBD-IS1	VIA/VIB	HS/LS	8	Y	N/A	N	SOIC-16 NB	2.5 kVrms
Si8274BB4D-IS1	PWM	HS/LS	8	Y	20-700	N	SOIC-16 NB	2.5 kVrms
Si8274DB4D-IS1	PWM	HS/LS	12	Y	20-700	N	SOIC-16 NB	2.5 kVrms
Si8275AB-IS1	VIA/VIB	Dual	5	N	N/A	Y	SOIC-16 NB	2.5 kVrms
Si8275ABD-IS1	VIA/VIB	Dual	5	Y	N/A	N	SOIC-16 NB	2.5 kVrms
Si8275BB-IS1	VIA/VIB	Dual	8	N	N/A	Y	SOIC-16 NB	2.5 kVrms
Si8275BBD-IS1	VIA/VIB	Dual	8	Y	N/A	N	SOIC-16 NB	2.5 kVrms
Si8275DB-IS1	VIA/VIB	Dual	12	N	N/A	Y	SOIC-16 NB	2.5 kVrms
Si8275DBD-IS1	VIA/VIB	Dual	12	Y	N/A	N	SOIC-16 NB	2.5 kVrms
Si8275BB-IM1	VIA/VIB	Dual	8	N	N/A	Y	QFN-14	2.5 kVrms
Si8275BBD-IM1	VIA/VIB	Dual	8	Y	N/A	N	QFN-14	2.5 kVrms
Si8275DB-IM1	VIA/VIB	Dual	12	N	N/A	Y	QFN-14	2.5 kVrms
Si8275DBD-IM1	VIA/VIB	Dual	12	Y	N/A	N	QFN-14	2.5 kVrms
Si8275GB-IM1	VIA/VIB	Dual	3	N	N/A	Y	QFN-14	2.5 kVrms
Si8275GBD-IM1	VIA/VIB	Dual	3	Y	N/A	N	QFN-14	2.5 kVrms
Si8275DA-IM1	VIA/VIB	Dual	12	N	N/A	Y	QFN-14	1 kVrms
Si8275DAD-IM1	VIA/VIB	Dual	12	Y	N/A	N	QFN-14	1 kVrms

**Automotive Grade OPNs**

Automotive-grade devices are built using automotive-specific flows at all steps in the manufacturing process to ensure robustness and low defectivity. These devices are supported with AIAG-compliant Production Part Approval Process (PPAP) documentation, and feature International Material Data System (IMDS) and China Automotive Material Data System (CAMDS) listing. Qualifications are compliant with AEC-Q100, and a zero-defect methodology is maintained throughout definition, design, evaluation, qualification, and mass production steps.

**Table 1.2. Ordering Guide for Automotive Grade OPNs<sup>1, 2, 4, 5</sup>**

Ordering Part Numbers (OPNs)	Inputs	Driver Configuration	Output UVLO	Integrated Deglitcher	Dead Time Adjustable Range	Low Jitter	Package	Isolation Rating
Si8271BB-AS	VI	Single	8	N	N/A	Y	SOIC-8 NB	2.5 kVrms
Si8271DB-AS	VI	Single	12	N	N/A	Y	SOIC-8 NB	2.5 kVrms
Si8273DB-AS1	VIA/VIB	HS/LS	12	N	N/A	Y	SOIC-16 NB	2.5 kVrms
Si8274DB1-AS1	PWM	HS/LS	12	N	10-100	Y	SOIC-16 NB	2.5 kVrms
Si8275DB-AS1	VIA/VIB	Dual	12	N	N/A	Y	SOIC-16 NB	2.5 kVrms

**Note:**

1. All packages are RoHS-compliant with peak reflow temperatures of 260 °C according to the JEDEC industry standard classifications.
2. "Si" and "SI" are used interchangeably.
3. An "R" at the end of the part number denotes tape and reel packaging option.
4. Automotive-Grade devices (with an "-A" suffix) are identical in construction materials, topside marking, and electrical parameters to their Industrial-Grade (with a "-I" suffix) version counterparts. Automotive-Grade products are produced utilizing full automotive process flows and additional statistical process controls throughout the manufacturing flow. The Automotive-Grade part number is included on shipping labels.
5. Additional Ordering Part Numbers may be available in Automotive-Grade. Please contact your local Silicon Labs sales representative for further information.
6. Referring to Section 8 Top Marking, the Manufacturing Code represented by either "RTTTTT" or "TTTTTT" contains as its first character a letter in the range N through Z to indicate Automotive-Grade.

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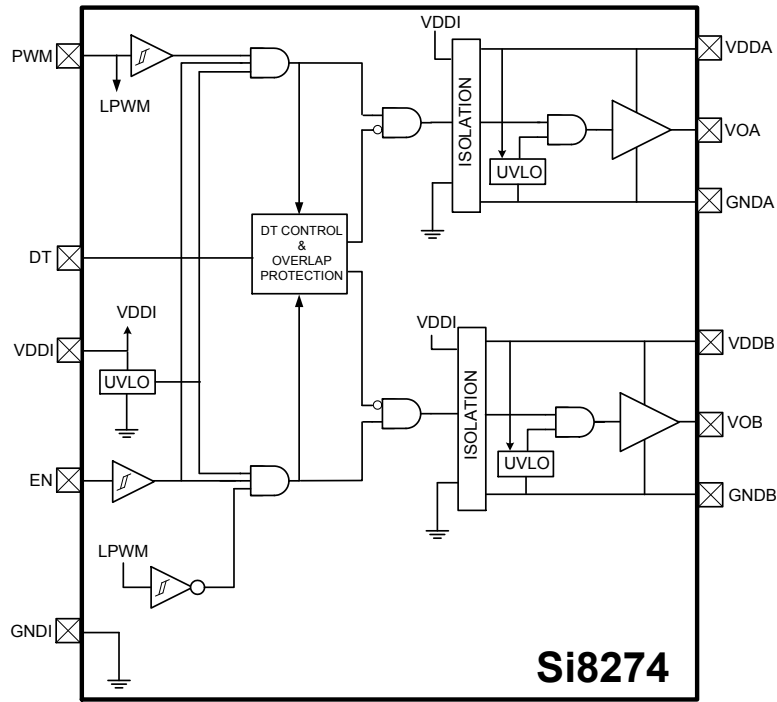


Figure 2.3. Si8274 Block Diagram

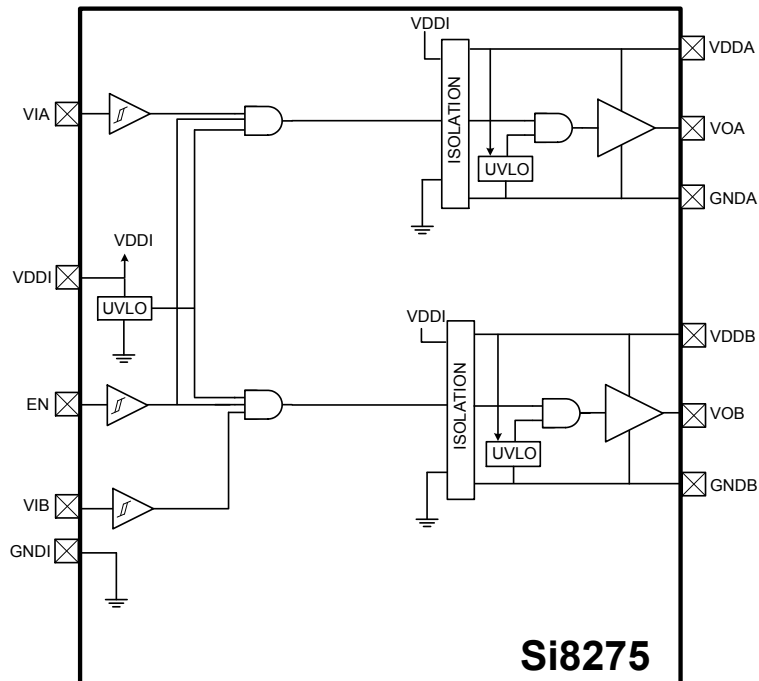


Figure 2.4. Si8275 Block Diagram

The operation of an Si827x channel is analogous to that of an optocoupler and gate driver, except an RF carrier is modulated instead of light. This simple architecture provides a robust isolated data path and requires no special considerations or initialization at start-up. A simplified block diagram for a single Si827x channel is shown in the figure below.

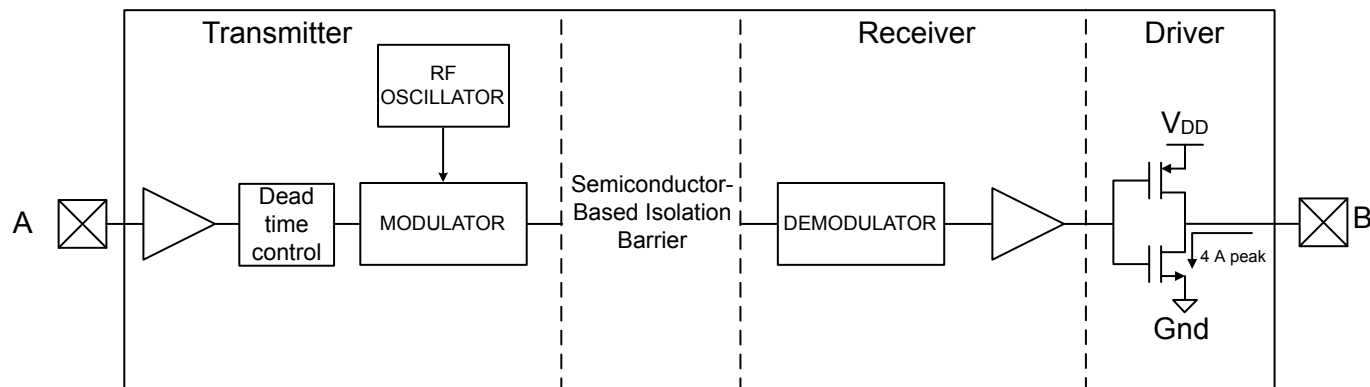


Figure 2.5. Simplified Channel Diagram

A channel consists of an RF Transmitter and RF Receiver separated by a semiconductor-based isolation barrier. Referring to the Transmitter, input A modulates the carrier provided by an RF oscillator using on/off keying. The Receiver contains a demodulator that decodes the input state according to its RF energy content and applies the result to output B via the output driver. This RF on/off keying scheme is superior to pulse code schemes as it provides best-in-class noise immunity, low power consumption, and better immunity to magnetic fields. See [Figure 2.6 Modulation Scheme on page 9](#) for more details.

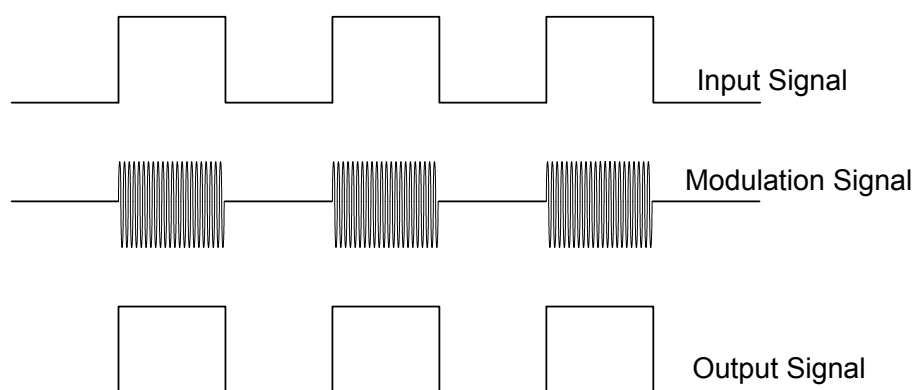


Figure 2.6. Modulation Scheme

## 2.1 Typical Operating Characteristics

The typical performance characteristics depicted in the figures below are for information purposes only. Refer to [Table 4.1 Electrical Characteristics](#) on page 20 for actual specification limits.

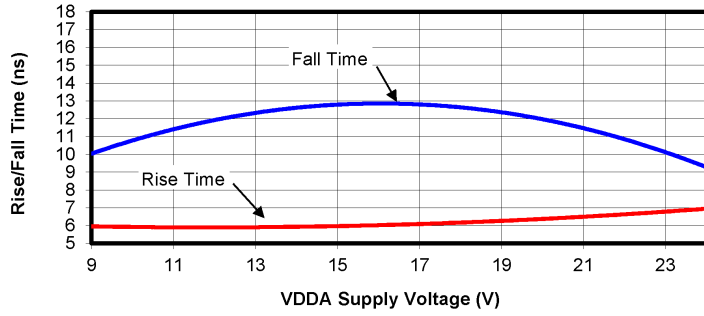


Figure 2.7. Rise/Fall Time vs. Supply Voltage

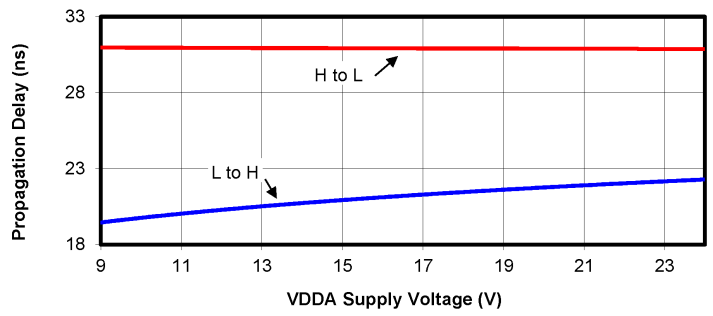


Figure 2.8. Propagation Delay vs. Supply Voltage

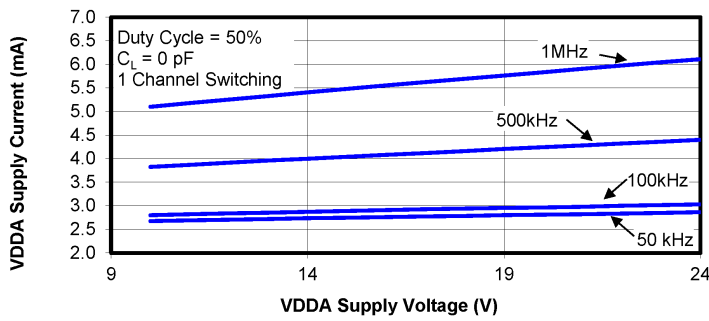


Figure 2.9. Supply Current vs. Supply Voltage

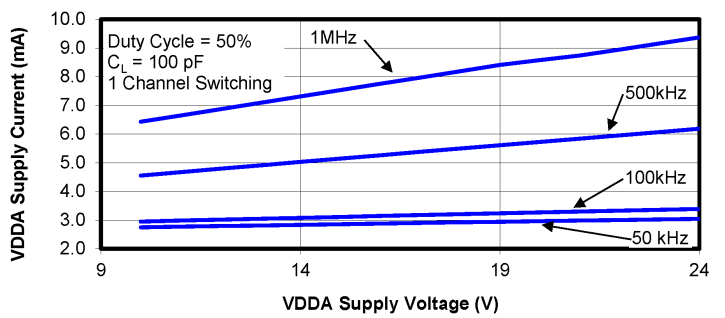


Figure 2.10. Supply Current vs. Supply Voltage

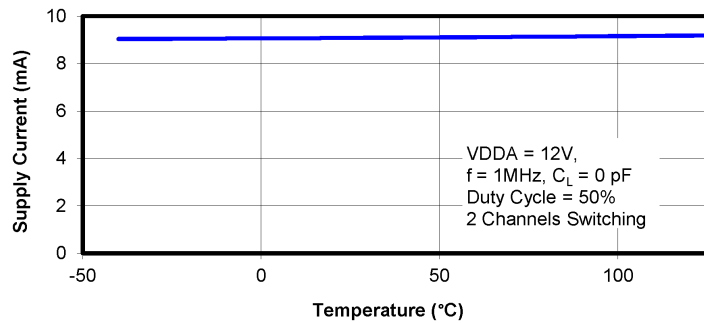


Figure 2.11. Supply Current vs. Temperature

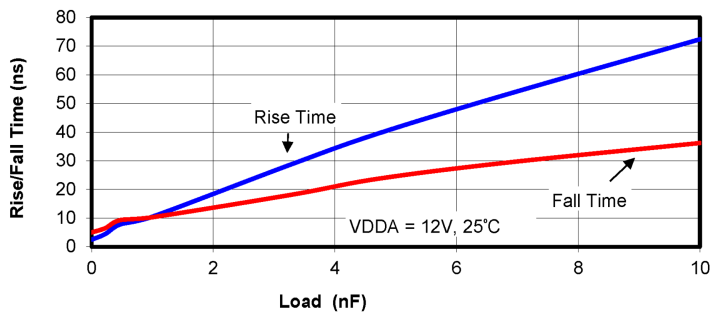


Figure 2.12. Rise/Fall Time vs. Load

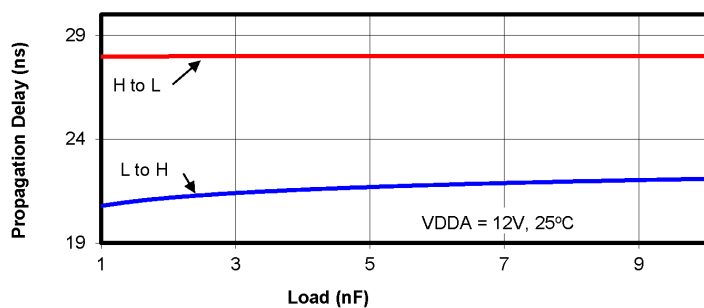


Figure 2.13. Propagation Delay vs. Load

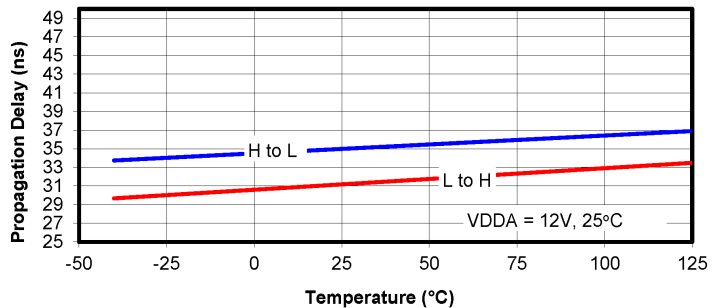


Figure 2.14. Propagation Delay vs. Temperature

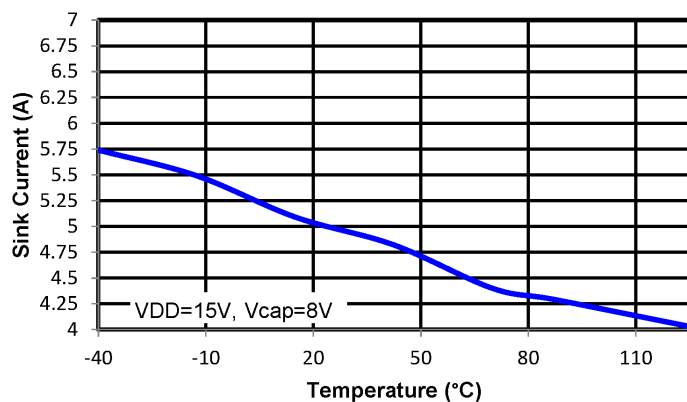


Figure 2.15. Output Sink Current vs. Temperature

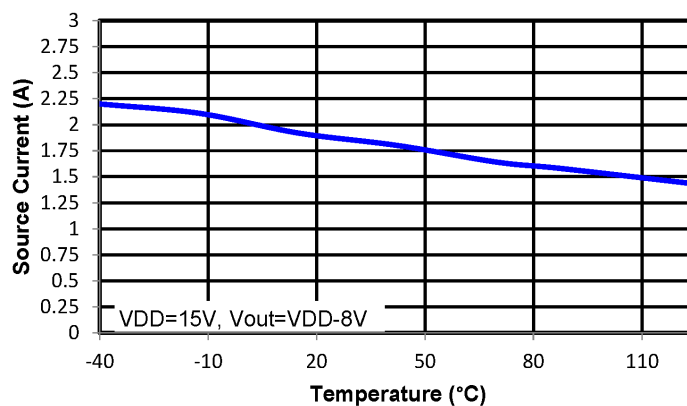


Figure 2.16. Output Source Current vs. Temperature

## 2.2 Family Overview and Logic Operation During Startup

The Si827x family of isolated drivers consists of single, high-side/low-side, and dual driver configurations.

### 2.2.1 Products

The table below shows the configuration and functional overview for each product in this family.

**Table 2.1. Si827x Family Overview**

Part Number	Configuration	Overlap Protection	Programmable Dead Time	Inputs	Peak Output Current (A)
Si8271	Single Driver	—	—	VI	4.0
Si8273	High-Side/Low-Side	Y	—	VIA, VIB	4.0
Si8274	PWM	Y	Y	PWM	4.0
Si8275	Dual Driver	—	—	VIA, VIB	4.0

### 2.2.2 Device Behavior

The following table consists of truth tables for the Si8273, Si8274, and Si8275 families.

Table 2.2. Si827x Family Truth Table<sup>1</sup>

Si8271 (Single Driver) Truth Table						
Inputs		VDDI State	Enable	Output		Notes
VI				VO+	VO-	
L		Powered	H	Hi-Z	L	
H		Powered	H	H	Hi-Z	
X <sup>2</sup>		Unpowered	X	Hi-Z	L	
X		Powered	L	Hi-Z	L	
Si8273 (High-Side/Low-Side) Truth Table						
Inputs		VDDI State	Enable	Output		Notes
VIA	VIB			VOA	VOB	
L	L	Powered	H	L	L	
L	H	Powered	H	L	H	
H	L	Powered	H	H	L	
H	H	Powered	H	L	L	Invalid state.
X <sup>2</sup>	X <sup>2</sup>	Unpowered	X	L	L	Output returns to input state within 7 $\mu$ s of VDDI power restoration.
X	X	Powered	L	L	L	Device is disabled.
Si8274 (PWM Input High-Side/Low-Side) Truth Table						
PWM Input		VDDI State	Enable	Output		Notes
				VOA	VOB	
H		Powered	H	H	L	
L		Powered	H	L	H	
X <sup>2</sup>		Unpowered	X	L	L	Output returns to input state within 7 $\mu$ s of VDDI power restoration.
X		Powered	L	L	L	Device is disabled.
Si8275 (Dual Driver) Truth Table						
Inputs		VDDI State	Enable	Output		Notes
VIA	VIB			VOA	VOB	
L	L	Powered	H	L	L	
L	H	Powered	H	L	H	
H	L	Powered	H	H	L	
H	H	Powered	H	H	H	
X <sup>2</sup>	X <sup>2</sup>	Unpowered	X	L	L	Output returns to input state within 7 $\mu$ s of VDDI power restoration.
X	X	Powered	L	L	L	Device is disabled.

1. This truth table assumes VDDA and VDDB are powered. If VDDA and VDDB are below UVLO, see [2.6.2 Undervoltage Lockout](#) for more information.

2. An input can power the input die through an internal diode if its source has adequate current.

## 2.3 Power Supply Connections

Isolation requirements mandate individual supplies for VDDI, VDDA, and VDDB. The decoupling caps for these supplies must be placed as close to the VDD and GND pins of the Si827x as possible. The optimum values for these capacitors depend on load current and the distance between the chip and the regulator that powers it. Low effective series resistance (ESR) capacitors, such as Tantalum, are recommended.

## 2.4 Power Dissipation Considerations

Proper system design must assure that the Si827x operates within safe thermal limits across the entire load range. The Si827x total power dissipation is the sum of the power dissipated by bias supply current, internal parasitic switching losses, and power dissipated by the series gate resistor and load. The equation below shows total Si827x power dissipation.

$$P_D = (V_{DDI})(I_{DDI}) + 2(I_{DD2})(V_{DD2}) + (f)(Q_G)\left(V_{DD2}\right)\left[\frac{R_p}{R_p + R_g}\right] + (f)(Q_G)\left(V_{DD2}\right)\left[\frac{R_n}{R_n + R_g}\right] + 2fC_{int}V_{DD2}^2$$

where:

$P_D$  is the total Si827x device power dissipation (W)

$I_{DDI}$  is the input-side maximum bias current (10 mA)

$I_{DD2}$  is the driver die maximum bias current (4 mA)

$C_{int}$  is the internal parasitic capacitance (370 pF)

$V_{DDI}$  is the input-side  $V_{DD}$  supply voltage (2.5 to 5.5 V)

$V_{DD2}$  is the driver-side supply voltage (4.2 to 30 V)

$f$  is the switching frequency (Hz)

$Q_G$  is the gate charge of external FET

$R_G$  is the external gate resistor

$R_p$  is the  $R_{DS(ON)}$  of the driver pull-up switch: 2.7  $\Omega$

$R_n$  is the  $R_{DS(ON)}$  of the driver pull-down switch: 1  $\Omega$

### Equation 1

Power dissipation example for driver using Equation 1 with the following givens:

$$V_{DDI} = 5.0 \text{ V}$$

$$V_{DD2} = 12 \text{ V}$$

$$f = 350 \text{ kHz}$$

$$R_G = 22 \text{ } \Omega$$

$$Q_G = 25 \text{ nC}$$

$$P_d = 199 \text{ mW}$$

From which the driver junction temperature is calculated using Equation 2, where:

$P_d$  is the total Si827x device power dissipation (W)

$\theta_{ja}$  is the thermal resistance from junction to air (105 °C/W in this example)

$T_A$  is the ambient temperature

$$T_j = P_d \times \theta_{ja} + T_A = (0.199)(105) + 20 = 41.0 \text{ } ^\circ \text{C}$$

The maximum power dissipation allowable for the Si827x is a function of the package thermal resistance, ambient temperature, and maximum allowable junction temperature, as shown in Equation 2:

$$P_{Dmax} \leq \frac{T_{jmax} - T_A}{\theta_{ja}}$$

where:

$P_{Dmax}$  = Maximum Si827x power dissipation (W)

$T_{jmax}$  = Si827x maximum junction temperature (150 °C)

$T_A$  = Ambient temperature (20 °C)

$\theta_{ja}$  = Si827x junction-to-air thermal resistance (105 °C/W)

### Equation 2

Substituting values for  $P_{Dmax}$ ,  $T_{jmax}$ ,  $T_A$ , and  $\theta_{ja}$  into Equation 2 results in a maximum allowable total power dissipation of 1.23 W. Maximum allowable load is found by substituting this limit and the appropriate data sheet values from [Table 4.1 Electrical Characteristics on page 20](#) into Equation 1 and simplifying. The result is Equation 3, which assumes  $V_{DDI} = 5\text{ V}$  and  $V_{DDA} = V_{DDB} = 12\text{ V}$ .

$$Q_{g(max)} = \frac{0.596}{f} - 5.81 \times 10^{-8}$$

### Equation 3

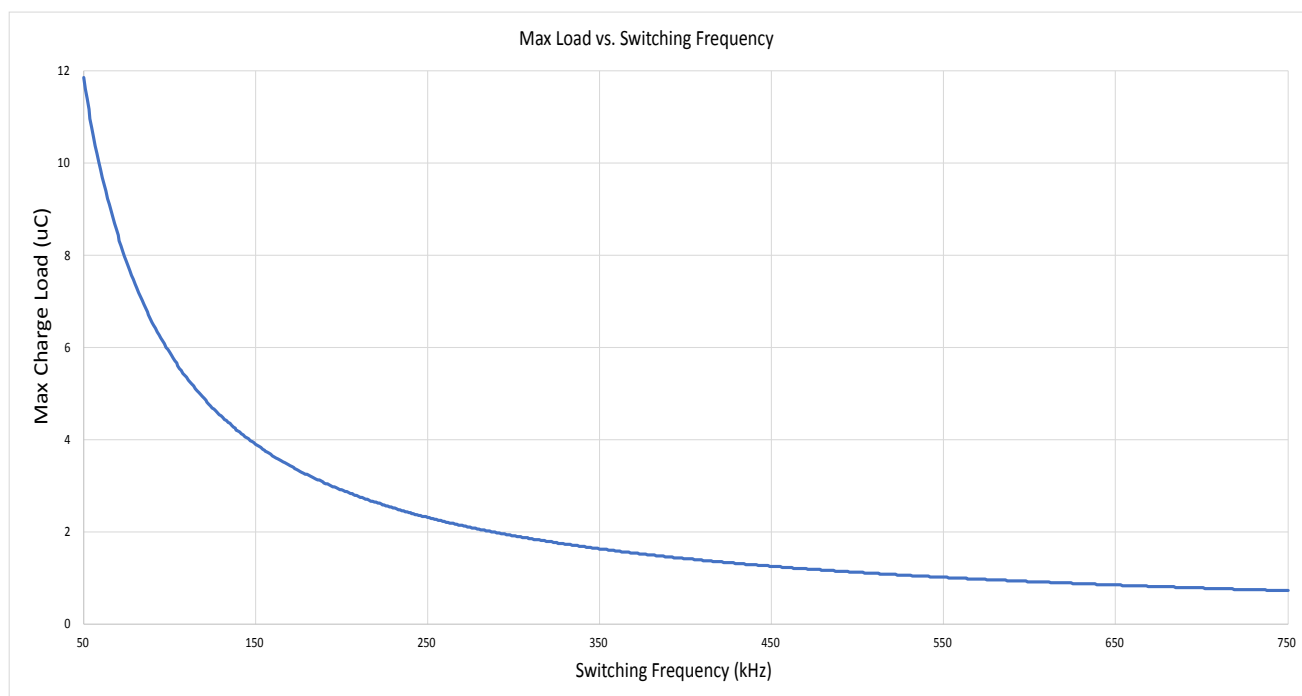


Figure 2.17. Max Load vs. Switching Frequency

## 2.5 Layout Considerations

It is most important to minimize ringing in the drive path and noise on the Si827x VDD lines. Care must be taken to minimize parasitic inductance in these paths by locating the Si827x as close to the device it is driving as possible. In addition, the VDD supply and ground trace paths must be kept short. For this reason, the use of power and ground planes is highly recommended. A split ground plane system having separate ground and VDD planes for power devices and small signal components provides the best overall noise performance.

## 2.6 Undervoltage Lockout Operation

Device behavior during start-up, normal operation and shutdown is shown in the figure below, where UVLO+ and UVLO- are the positive-going and negative-going thresholds respectively.

**Note:** Outputs VOA and VOB default low when input side power supply (VDDI) is not present.

### 2.6.1 Device Startup

Outputs VOA and VOB are held low during power-up until VDD is above the UVLO threshold for time period  $t_{START}$ . Following this, the outputs follow the states of inputs VIA and VIB.

### 2.6.2 Undervoltage Lockout

Undervoltage Lockout (UVLO) is provided to prevent erroneous operation during device startup and shutdown or when VDD is below its specified operating circuits range. The input (control) side, Driver A and Driver B, each have their own undervoltage lockout monitors.

The Si827x input side enters UVLO when  $VDDI < VDDI_{UV-}$ , and exits UVLO when  $VDDI > VDDI_{UV+}$ . The driver outputs, VOA and VOB, remain low when the input side of the Si827x is in UVLO and their respective VDD supply (VDDA, VDDDB) is within tolerance. Each driver output can enter or exit UVLO independently. For example, VOA unconditionally enters UVLO when VDDA falls below  $VDDA_{UV-}$  and exits UVLO when VDDA rises above  $VDDA_{UV+}$ .

The UVLO circuit unconditionally drives VO low when VDD is below the lockout threshold. Upon power up, the Si827x is maintained in UVLO until VDD rises above  $VDD_{UV+}$ . During power down, the Si827x enters UVLO when VDD falls below the UVLO threshold plus hysteresis (i.e.,  $VDD < VDD_{UV+} - VDD_{HYS}$ ). Please refer to spec tables for UVLO values.

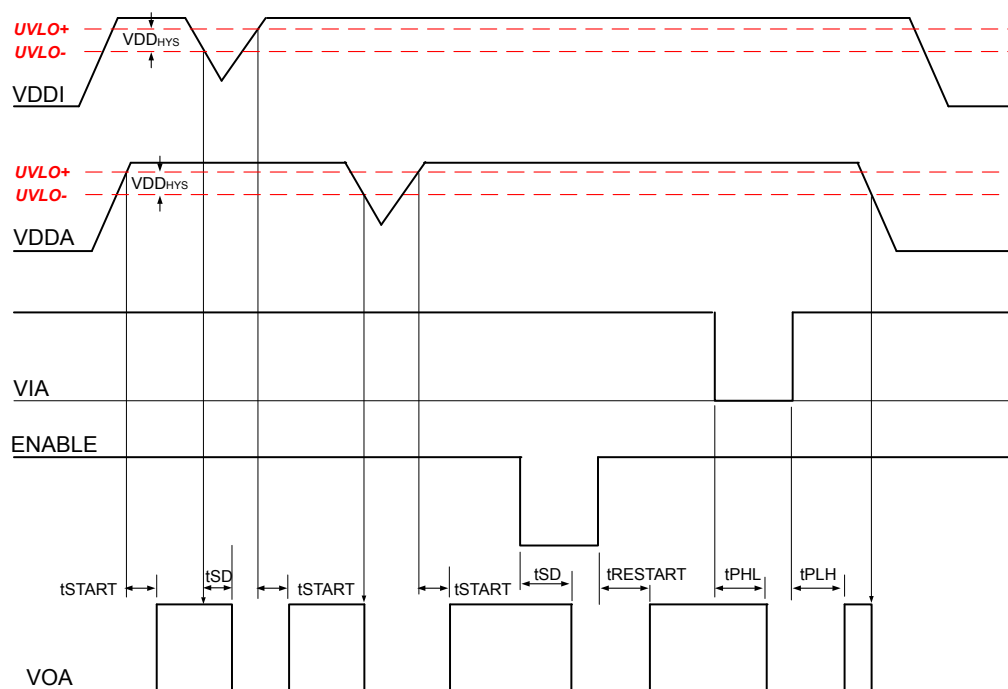


Figure 2.18. Device Behavior during Normal Operation and Shutdown

### 2.6.3 Control Inputs

VIA, VIB, and PWM inputs are high-true, TTL level-compatible logic inputs. A logic high signal on VIA or VIB causes the corresponding output to go high. For PWM input versions (Si8274), VOA is high and VOB is low when the PWM input is high, and VOA is low and VOB is high when the PWM input is low.



## 2.6.4 Enable Input

When brought low, the ENABLE input unconditionally drives VOA and VOB low regardless of the states of VIA and VIB. Device operation terminates within  $t_{SD}$  after  $ENABLE = V_{IL}$  and resumes within  $t_{RESTART}$  after  $ENABLE = V_{IH}$ . The ENABLE input has no effect if VDDI is below its UVLO level (i.e., VOA, VOB remain low).

## 2.7 Programmable Dead Time and Overlap Protection

All PWM drivers (Si8274x) include programmable dead time, which adds a user-programmable delay between transitions of VOA and VOB. When enabled, dead time is present on all transitions. The amount of dead time delay (DT) is programmed by a single resistor (RDT) connected from the DT input to ground per the equation below.

$$DT = 2.02 \times RDT + 7.77 \text{ (for 10-200 ns range)}$$

$$DT = 6.06 \times RDT + 3.84 \text{ (for 20-700 ns range)}$$

where:

DT = dead time (ns)

and

RDT = dead time programming resistor (k $\Omega$ )

### Equation 4

Input/output timing waveforms for the Si8273 two-input drivers are shown in the figure below, and dead time waveforms for the Si8274 are shown in [Figure 2.20 Dead Time Waveforms for Si8274 Drivers on page 17](#).

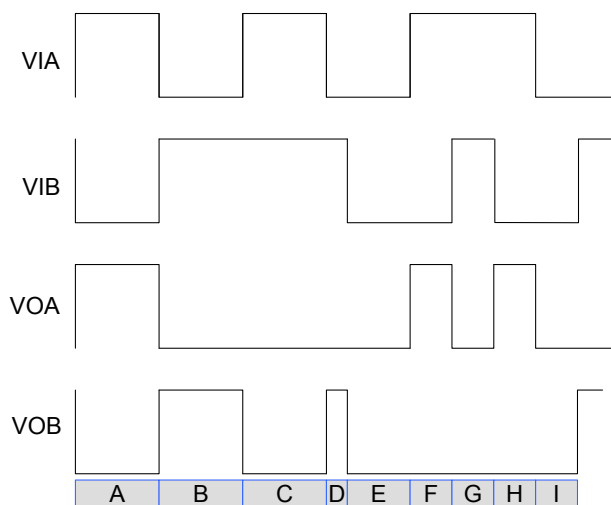
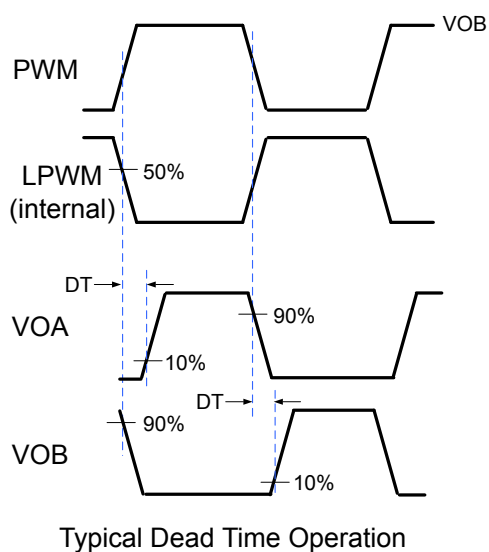


Figure 2.19. Input / Output Waveforms for Si8273 Drivers

**Table 2.3. Input / Output Waveforms for High-Side / Low-Side Two-Input Drivers**

Ref	Description
A	Normal operation: VIA high, VIB low.
B	Normal operation: VIB high, VIA low.
C	Contention: VIA = VIB = high.
D	Recovery from contention: VIA transitions low.
E	Normal operation: VIA = VIB = low.
F	Normal operation: VIA high, VIB low.
G	Contention: VIA = VIB = high.
H	Recovery from contention: VIB transitions low.
I	Normal operation: VIB transitions high.

**Figure 2.20. Dead Time Waveforms for Si8274 Drivers**

## 2.8 De-glitch Feature

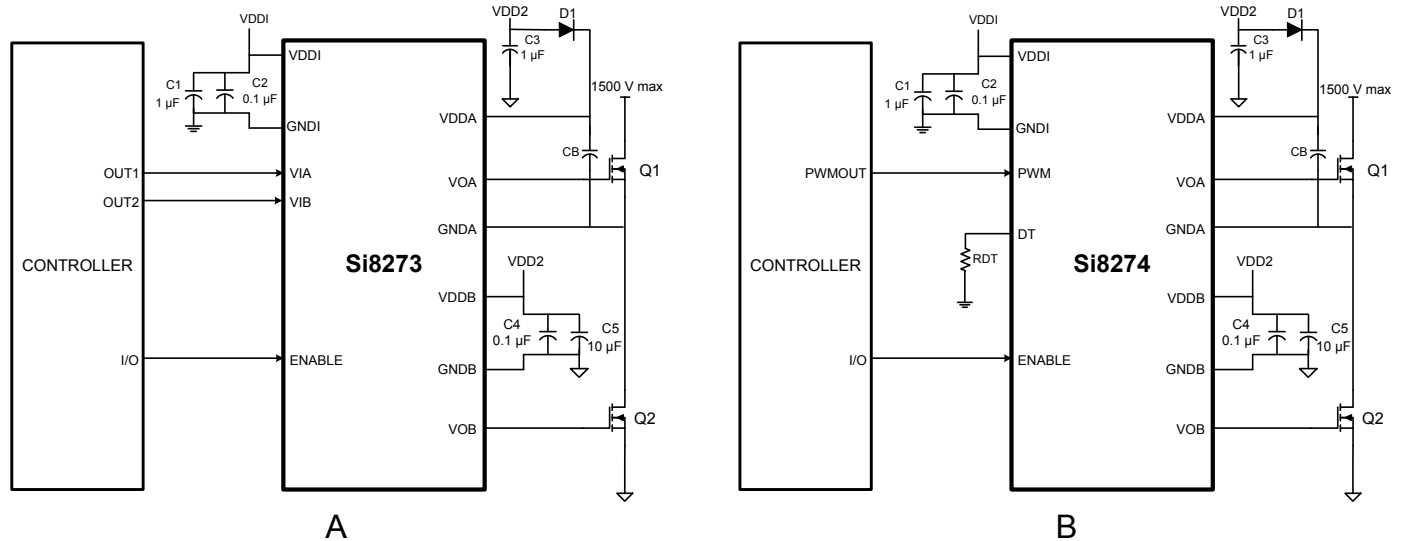
A de-glitch feature is provided on some options, as defined in the [1. Ordering Guide](#). The internal de-glitch circuit provides an internal time delay of 15 ns typical, during which any noise is ignored and will not pass through the IC. For these product options, the propagation delay will be extended by 15 ns, as specified in the spec table.

### 3. Applications

The following examples illustrate typical circuit configurations using the Si827x.

#### 3.1 High-Side/Low-Side Driver

In the figure below, side A shows the Si8273 controlled using the VIA and VIB input signals, and side B shows the Si8274 controlled by a single PWM signal.

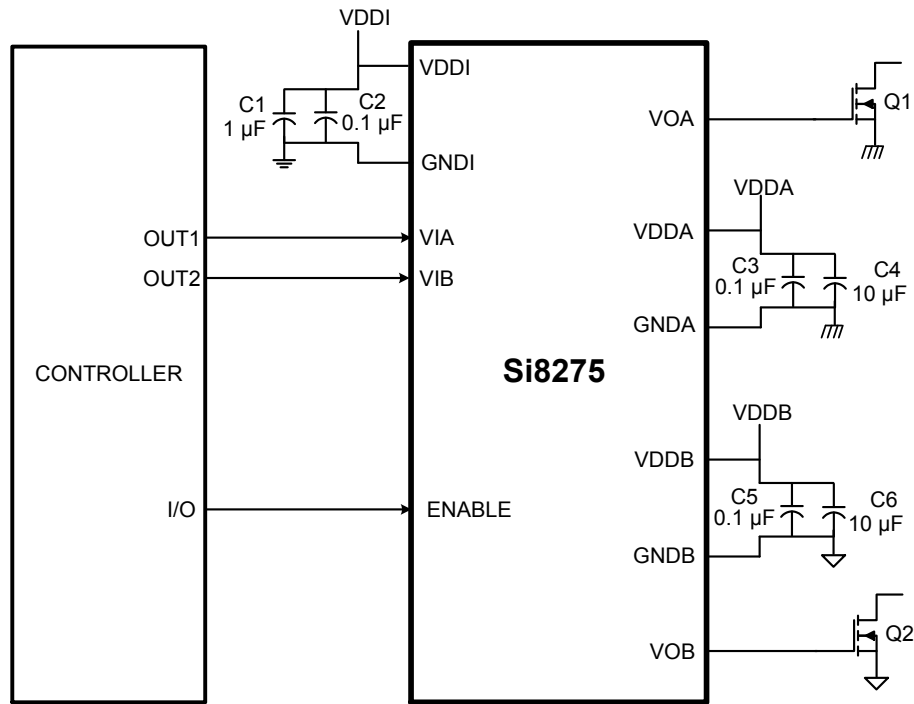


**Figure 3.1. Si827x in Half-Bridge Application**

For both cases, D1 and CB form a conventional bootstrap circuit that allows VOA to operate as a high-side driver for Q1, which has a maximum drain voltage of 1500 V. VOB is connected as a conventional low-side driver. Note that the input side of the Si827x requires VDD in the range of 2.5 to 5.5 V, while the VDDA and VDDB output side supplies must be between 4.2 and 30 V with respect to their respective grounds. The boot-strap start up time will depend on the CB cap chosen. VDD2 is usually the same as VDDB. Also note that the bypass capacitors on the Si827x should be located as close to the chip as possible. Moreover, it is recommended that bypass capacitors be used (as shown in the figures above for input and driver side) to reduce high frequency noise and maximize performance. The outputs VOA and VOB can be used interchangeably as high side or low side drivers.

### 3.2 Dual Driver

The figure below shows the Si827x configured as a dual driver. Note that the drain voltages of Q1 and Q2 can be referenced to a common ground or to different grounds with as much as 1500 V dc between them.



**Figure 3.2. Si827x in a Dual Driver Application**

Because each output driver resides on its own die, the relative voltage polarities of VOA and VOB can reverse without damaging the driver. That is, the voltage at VOA can be higher or lower than that of VOB by VDD without damaging the driver. Therefore, a dual driver in a high-side/low-side drive application can use either VOA or VOB as the high side driver. Similarly, a dual driver can operate as a dual low-side or dual high-side driver and is unaffected by static or dynamic voltage polarity changes.

## 4. Electrical Specifications

**Table 4.1. Electrical Characteristics**

$V_{DDI} = 5\text{ V}$ ,  $GNDI = 0\text{ V}$ ,  $V_{DDA/B-GNDA/B} = 30\text{ V}$ ,  $T_A = -40\text{ to }+125\text{ }^\circ\text{C}$ ; typical specs at  $25\text{ }^\circ\text{C}$

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>DC Parameters</b>						
Input Supply Voltage	VDDI		2.5	—	5.5	V
Driver Supply Voltage	(VDDA/B – GNDA/B)		4.2	—	30	V
Input Supply Quiescent Current	IDDI(Q)		—	7.9	10.0	mA
Input Supply Active Current	IDDI	f = 500 kHz	—	8.0	10.0	mA
Output Supply Quiescent Current	IDDX(Q)		—	2.5	4.0	mA
Output Supply Active Current	IDDX	f = 500 kHz (no load)	—	10.0	11.0	mA
<b>Gate Driver</b>						
High Output Transistor RDS (ON)	R <sub>OH</sub>		—	2.7	—	Ω
Low Output Transistor RDS (ON)	R <sub>OL</sub>		—	1.0	—	Ω
High Level Peak Output Current	I <sub>OH</sub>	V <sub>DDA/B</sub> = 15 V, See Figure 4.2 I <sub>OH</sub> Source Current Test Circuit on page 23 for Si827xG, V <sub>DD</sub> = 4.2 V, T < 250 ns	—	1.8	—	A
Low Level Peak Output Current	I <sub>OL</sub>	V <sub>DDA/B</sub> = 15 V, See Figure 4.1 I <sub>OL</sub> Sink Current Test Circuit on page 23 for Si827xG, V <sub>DD</sub> = 4.2 V, T <sub>PW_IOL</sub> < 250 ns	—	4.0	—	A
<b>UVLO</b>						
VDDI UVLO Threshold +	VDDI <sub>UV+</sub>		1.85	2.2	2.45	V
VDDI UVLO Threshold –	VDDI <sub>UV-</sub>		1.75	2.1	2.35	V
VDDI Hysteresis	VDDI <sub>HYS</sub>		—	100	—	mV
<b>UVLO Threshold + (Driver Side)</b>						
3 V Threshold	VDDX <sub>UV+</sub>		2.7	3.5	4.0	V
5 V Threshold			4.9	5.5	6.3	V
8 V Threshold			7.2	8.3	9.5	V
12 V Threshold			11	12.2	13.5	V
<b>UVLO Threshold - (Driver Side)</b>						

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
3 V Threshold	VDD <sub>XUV-</sub>		2.5	3.0	3.8	V
5 V Threshold			4.6	5.2	5.9	V
8 V Threshold			6.7	7.8	8.9	V
12 V Threshold			9.6	10.8	12.1	V
<b>UVLO Lockout Hysteresis</b>						
3 V Threshold	VDD <sub>HYS</sub>		—	500	—	mV
5 V Threshold			—	300	—	mV
8 V Threshold			—	500	—	mV
12 V Threshold			—	1400	—	mV
<b>Digital</b>						
Logic High Input Threshold	V <sub>IH</sub>		2.0	—	—	V
Logic Low Input Threshold	V <sub>IL</sub>		—	—	0.8	V
Input Hysteresis	V <sub>IHYST</sub>		350	400	—	mV
Logic High Output Voltage	V <sub>OH</sub>	IO = -1 mA	V <sub>DDA/B</sub> - 0.04	—	—	V
Logic Low Output Voltage	V <sub>OL</sub>	IO = 1 mA	—	—	0.04	V
<b>AC Switching Parameters</b>						
Propagation Delay Si8271/3/5 with low jitter	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 200 pF	20	30	60	ns
Propagation Delay Si8271/3/5 with de-glitch option	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 200 pF	30	45	75	ns
Propagation Delay Si8274 with low jitter	t <sub>PHL</sub>	C <sub>L</sub> = 200 pF	20	30	60	ns
Propagation Delay Si8274 with de-glitch option	t <sub>PHL</sub>	C <sub>L</sub> = 200 pF	30	45	75	ns
Propagation Delay Si8274 with low jitter	t <sub>PLH</sub>	C <sub>L</sub> = 200 pF	30	45	75	ns
Propagation Delay Si8274 with de-glitch option	t <sub>PLH</sub>	C <sub>L</sub> = 200 pF	65	85	105	ns
Pulse Width Distortion Si8271/3/5 all options	PWD	t <sub>PLH</sub> - t <sub>PHL</sub>	—	3.6	8	ns
Pulse Width Distortion Si8274 with low jitter	PWD	t <sub>PLH</sub> - t <sub>PHL</sub>	—	14	19	ns
Pulse Width Distortion Si8274 with de-glitch option	PWD	t <sub>PLH</sub> - t <sub>PHL</sub>	—	38	47	ns
Peak to Peak Jitter Si827x with low jitter			—	200	—	ps

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Programmed dead-time (DT) for products with 10–200 ns DT range	DT	RDT = 6 k $\Omega$	10	20	30	ns
		RDT = 15 k $\Omega$	26	38	50	
		RDT = 100 k $\Omega$	150	210	260	
Programmed dead-time (DT) for products with 20–700 ns DT range	DT	RDT = 6 k $\Omega$	23	40	57	ns
		RDT = 15 k $\Omega$	60	95	130	
		RDT = 100 k $\Omega$	450	610	770	
Rise time	$t_R$	CL = 200 pF	4	10.5	16	ns
Fall time	$t_F$	CL = 200 pF	5.5	13.3	18	ns
Shutdown Time from Enable False	$t_{SD}$		—	—	60	ns
Restart Time from Enable True	$t_{RESTART}$		—	—	60	ns
Device Startup Time	$t_{START}$		—	16	30	$\mu$ s
Common Mode Transient Immunity Si827x with de-glitch option		See <a href="#">Figure 4.3 Common Mode Transient Immunity Test Circuit on page 24</a> .  VCM = 1500 V	200	350	400	kV/ $\mu$ s
Common Mode Transient Immunity Si827x with low jitter option		See <a href="#">Figure 4.3 Common Mode Transient Immunity Test Circuit on page 24</a> .  VCM = 1500 V	150	300	400	kV/ $\mu$ s

### 4.1 Test Circuits

The figures below depict sink current, source current, and common-mode transient immunity test circuits.

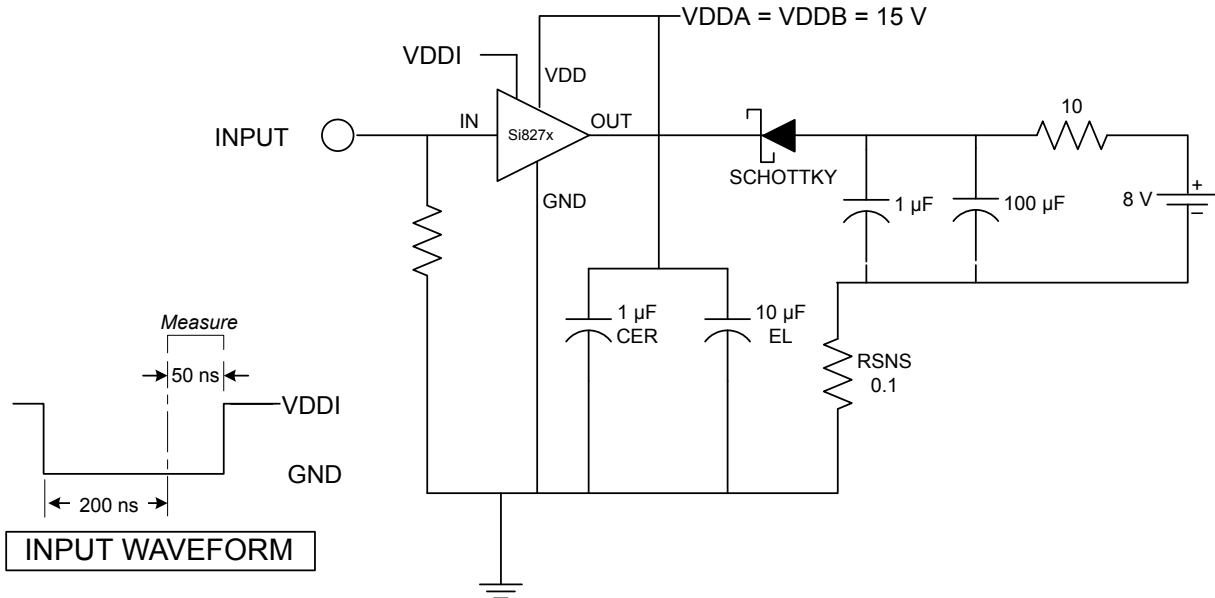


Figure 4.1. IOL Sink Current Test Circuit

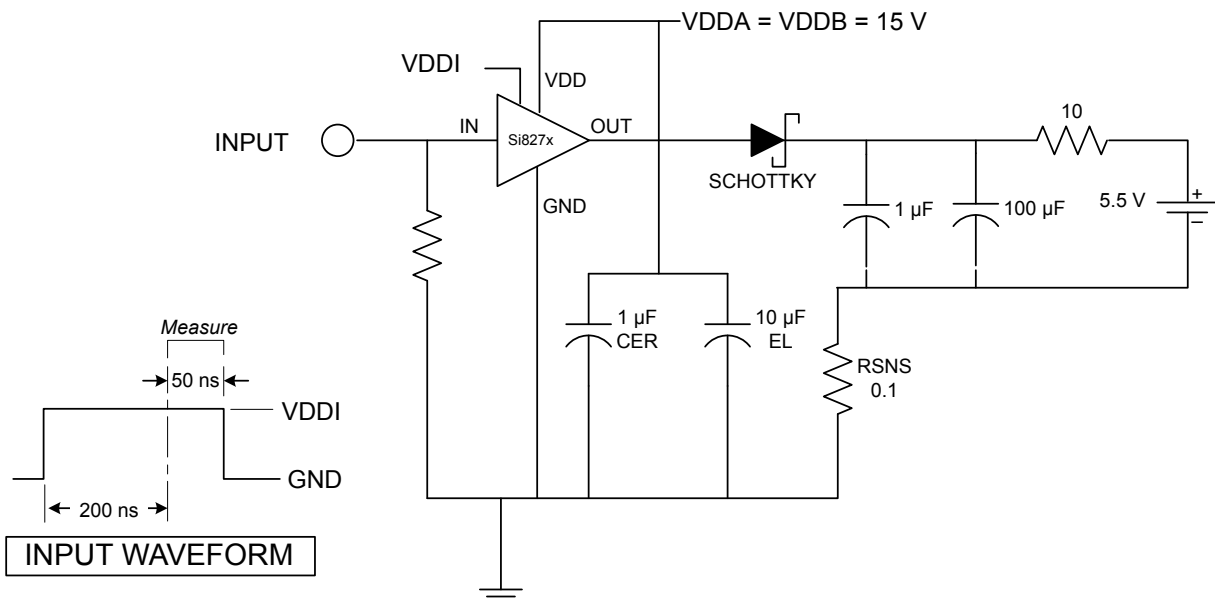


Figure 4.2. IOH Source Current Test Circuit



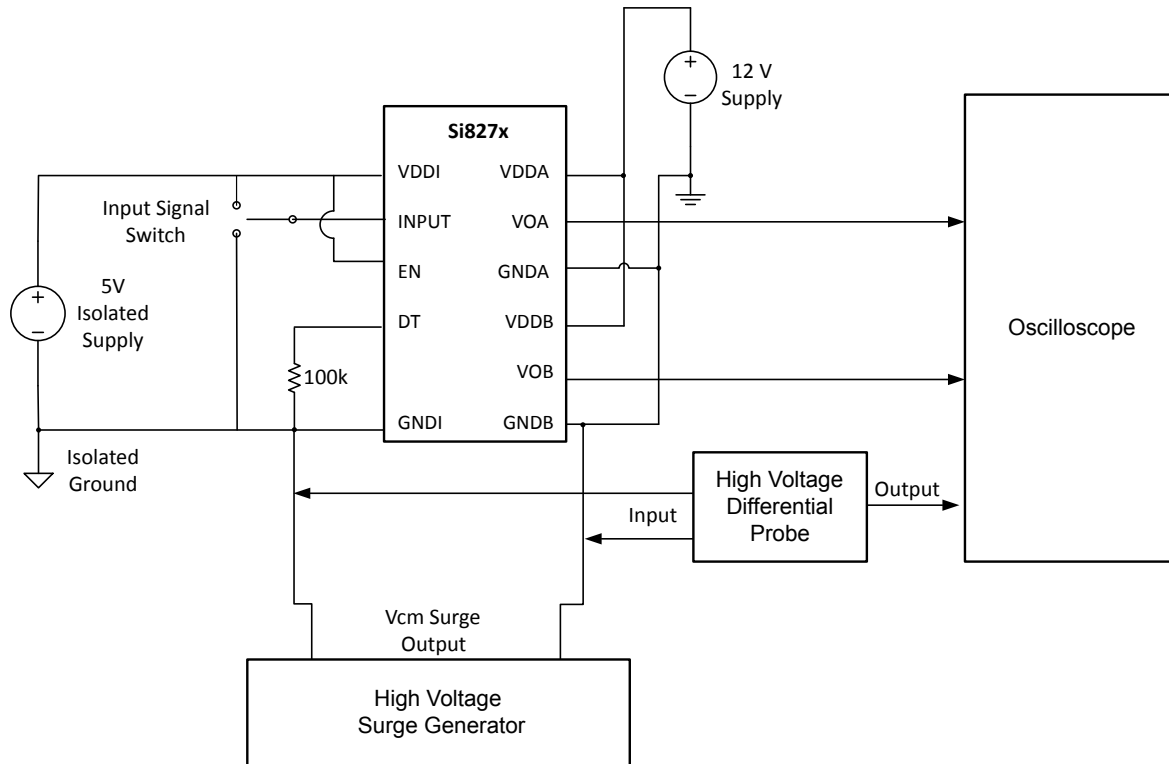


Figure 4.3. Common Mode Transient Immunity Test Circuit

#### 4.2 Regulatory Information (Pending)

Table 4.2. Regulatory Information<sup>1,2</sup>

<b>CSA</b>
The Si827x is certified under CSA Component Acceptance Notice 5A. For more details, see Master Contract Number 232873.
60950-1: Up to 125 V <sub>RMS</sub> reinforced insulation working voltage; up to 600 V <sub>RMS</sub> basic insulation working voltage.
<b>VDE</b>
The Si827x is certified according to VDE 0884-10. For more details, see Certificate 40018443.
VDE 0884-10: Up to 630 V <sub>peak</sub> for basic insulation working voltage.
<b>UL</b>
The Si827x is certified under UL1577 component recognition program. For more details, see File E257455.
Rated up to 2500 V <sub>RMS</sub> isolation voltage for basic protection.
<b>CQC</b>
The Si827x is certified under GB4943.1-2011. For more details, see Certificates CQC 16001160284 and CQC 17001177887.
Rated up to 125 V <sub>RMS</sub> reinforced insulation working voltage; up to 600 V <sub>RMS</sub> basic insulation working voltage.
1. Regulatory Certifications apply to 2.5 kV <sub>RMS</sub> rated devices which are production tested to 3.0 kV <sub>RMS</sub> for 1 sec.
2. For more information, see <a href="#">1. Ordering Guide</a> .

**Table 4.3. Insulation and Safety-Related Specifications**

Parameter	Symbol	Test Condition	Value			Unit
			SOIC-8	NB SOIC-16	14 LD QFN	
Nominal External Air Gap (Clearance)	CLR		4.7	4.7	3.5	mm
Nominal External Tracking (Creepage)	CPG		3.9	3.9	3.5	mm
Minimum Internal Gap (Internal Clearance)	DTI		0.008	0.008	0.008	mm
Tracking Resistance	PTI or CTI	IEC60112	600	600	600	V
Erosion Depth	ED		0.019	0.019	0.021	mm
Resistance (Input-Output) <sup>1</sup>	R <sub>IO</sub>		10 <sup>12</sup>	10 <sup>12</sup>	10 <sup>12</sup>	Ω
Capacitance (Input-Output) <sup>1</sup>	C <sub>IO</sub>	f = 1 MHz	0.5	0.5	0.5	pF
Input Capacitance <sup>2</sup>	C <sub>I</sub>		3.0	3.0	3.0	pF

**Notes:**

- To determine resistance and capacitance, the Si827x is converted into a 2-terminal device. All pins on side 1 are shorted to create terminal 1, and all pins on side 2 are shorted to create terminal 2. The parameters are then measured between these two terminals.
- Measured from input pin to ground.

**Table 4.4. IEC 60664-1 Ratings**

Parameter	Test Condition	Specification		
		SOIC-8	NB SOIC-16	14 LD QFN
Basic Isolation Group	Material Group	I	I	I
Installation Classification	Rated Mains Voltages < 150 V <sub>RMS</sub>	I-IV	I-IV	I-IV
	Rated Mains Voltages < 300 V <sub>RMS</sub>	I-III	I-III	I-III
	Rated Mains Voltages < 400 V <sub>RMS</sub>	I-II	I-II	I-II
	Rated Mains Voltages < 600 V <sub>RMS</sub>	I-II	I-II	I-II